CARDAG Deutschland GmbH

Product Information Dual-Interface Card – Cardag DIS

Property	Standard card*
Material	Modified PVC for high temperature usage
Colour	White, opaque
Surface	40 µm PVC Overlay
Dimension	ISO 7810 ID-1
Card Thickness	0,80 ±0,04 mm
Temperature of continuous usage	70 °C
Resistance to temperature (one side fixed)	70 °C
Module contacts	ISO 7816
Surface lamination	glossy, others on request
Connecting technology antenna – module	soldering
Antenna and contact pad technology	Embedded wire and welding
Printed cards	Offset beneath the overlay
Signature panel	transparent (hotstamped), others on request
Magnetic stripe	300 Oe, 2750 Oe, 4000 Oe
Subsequent printability	Thermotransfer or dye sublimation processes
Supplied material	8-contact modules from NXP and Infineon others on request

* Possible options are always subject to feasibility, especially in combination with other options

NXP Smart MX / Smart MX2 (ISO 14443A)
OS: JCOP / JCOP3 / MTCOS / TCOS

Infineon SLE77xx / SLE78xx (ISO 14443 A/B)
OS: JTOP / CardOS / TCOS

and applets on these processors for example
Legic Card-in-Card, Calypso / Cipurse

Additional features:
please turn the page

TRUB by Gemalto

Absolute Access

CARDAG Deutschland GmbH

Magnetic Stripes

Signature Panels

Holograms

Thermo-Re-Writable Foils

Special Prints & Effects

Number Printing / Lasering

SIM Punches / Special Cards

Lamination Surfaces